

SM8S33A-AM



Appearance & Shape



注意 NOTICE: All Specifications are subject to change without notice.

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2. 本文件僅說明參考標準規格，如需訂購，請依實際核准所需規格進行申辦。

Specification

L size(mm)	16
W size(mm)	10.5
T size(mm)	5.2
Size codeInch (mm)	DO-218
Direction Bi/Uni	Uni Direction
Channel	1
VRWM (V) Max	33
VB(V) Typical	36.7
VB(V) Max	40.6
Ipp (A)	53.3
Ppp (W)	6600

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Notices

Glass passivated chip junction

Reliable low cost construction utilizing molded plastic technique

Excellent clamping voltage capability

Fast response time

Meet ISO 7637-2 5a/5b and ISO 16750 load dump test (varied by test condition)

Packing

Packing Reel (Inch)	Carrier tape	Standard package quantity (KPCS)	Piece weight (gram)	MSL Level
13	Plastic type	0.75	2.86	1

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